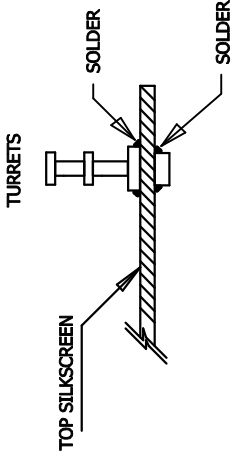


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 deg C.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.



APPROVALS		LINEAR TECHNOLOGY		1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)322-1900 www.linear.com LTC CONFIDENTIAL - FOR CUSTOMER USE ONLY	
PCB DES.		TITLE: TOP ASSEMBLY DRAWING		45V VIN, MICROPOWER, LOW NOISE 200mA LDO WITH OUTPUT DISCHARGE	
APP ENG.					
				SIZE	IC NO. LT3061EDC/LT3062EDC/LT3063EDC
				N/A	REV. 2
SCALE = NONE		FILENAME: 2177A-Rev2.PCB		SHT 1 OF 1	

ASSY	U1	IOUT	OUTPUT DISCHARGE
-A	LT3061EDCB	100mA	YES
-B	LT3062EDCB	200mA	NO
-C	LT3063EDCB	200mA	YES